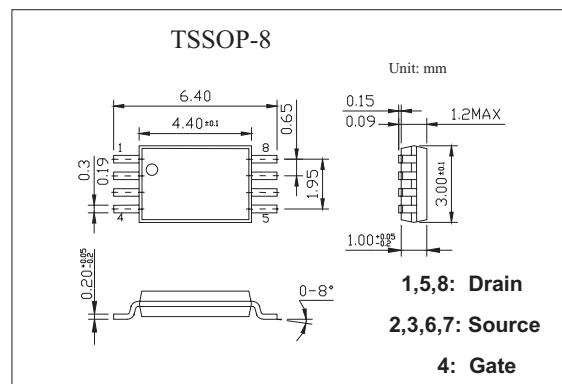
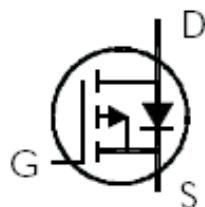


## HEXFET® Power MOSFET

### KRF7706

#### ■ Features

- Ultra Low On-Resistance
- P-Channel MOSFET
- Very Small SOIC Package
- Low Profile (< 1.2mm)
- Available in Tape & Reel



#### ■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	Rating	Unit
Drain- Source Voltage	V <sub>DS</sub>	-30	V
Continuous Drain Current, V <sub>GS</sub> @ -10V @ T <sub>a</sub> = 25°C	I <sub>D</sub>	-7	A
Continuous Drain Current, V <sub>GS</sub> @ -10V @ T <sub>a</sub> = 70°C	I <sub>D</sub>	-5.7	
Pulsed Drain Current *1	I <sub>DM</sub>	-28	
Power Dissipation *2 @T <sub>a</sub> = 25°C	P <sub>D</sub>	1.51	W
Power Dissipation *2 @T <sub>a</sub> = 70°C	P <sub>D</sub>	0.96	W
Linear Derating Factor		0.01	W/°C
Gate-to-Source Voltage	V <sub>GS</sub>	±20	V
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to + 150	°C
Maximum Junction-to-Ambient *2	R <sub>θ JA</sub>	83	°C/W

\*1 Repetitive rating; pulse width limited by max. junction temperature.

\*2 Surface mounted on 1 in square Cu board

**KRF7706**

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250 μ A	-30			V
Breakdown Voltage Temp. Coefficient	△V <sub>(BR)DSS</sub> /△T <sub>J</sub>	I <sub>D</sub> = -1mA, Reference to 25°C		0.015		V/°C
Static Drain-to-Source On-Resistance	R <sub>D(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -7.0A*1			22	m Ω
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -5.6A*1			36	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250 μ A	-1.0		-2.5	V
Forward Transconductance	g <sub>fs</sub>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -7.0A*1	6.9			S
Drain-to-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> = -24V, V <sub>GS</sub> = 0V			-15	μ A
		V <sub>DS</sub> = -24V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 70°C			-25	
Gate-to-Source Forward Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = -20V			-100	nA
Gate-to-Source Reverse Leakage		V <sub>GS</sub> = 20V			100	
Total Gate Charge	Q <sub>g</sub>	I <sub>D</sub> = -7.0A		48	72	nC
Gate-to-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = -15V		8.5		
Gate-to-Drain ("Miller") Charge	Q <sub>gd</sub>	V <sub>GS</sub> = -10V		8.4		
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = -15V, V <sub>GS</sub> = -10V		17		ns
Rise Time	t <sub>r</sub>	I <sub>D</sub> = -1.0A		46		
Turn-Off Delay Time	t <sub>d(off)</sub>	R <sub>G</sub> = 6 Ω		244		
Fall Time	t <sub>f</sub>	R <sub>D</sub> = 15 Ω		122		
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V		2211		pF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = -25V		339		
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		207		
Continuous Source Current (Body Diode)	I <sub>s</sub>	MOSFET symbol showing the integral reverse p-n junction diode.			-1.5	A
Pulsed Source Current (Body Diode) *2	I <sub>SM</sub>				-28	
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25°C, I <sub>s</sub> = -1.5A, V <sub>GS</sub> = 0V*1			-1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = -1.5A		34	51	ns
Reverse RecoveryCharge	Q <sub>rr</sub>	dI/dt = -100A/ μ s*1		32	48	μ C

\*1 Pulse width ≤ 300 μ s; duty cycle ≤ 2%.

\*2 Repetitive rating; pulse width limited by max. junction temperature.